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(54) **METHOD FOR MANUFACTURING THERMOELECTRIC CONVERTER**

(57) An insulating substrate (10) is prepared. In the substrate, plurality via holes (11 and 12) penetrating in a thickness direction are filled with a conductive paste (41 and 51). This paste is produced by adding an organic solvent to a powder of an alloy in which a plurality of metal atoms retain a predetermined crystalline structure, and by processing the powder to a paste. The insulating substrate (10) is then pressed from a front surface (10a) and a back surface (10b) of the insulating substrate (10), while being heated. The conductive paste (41 and 51) is solid-phase sintered and interlayer connecting members

(40 and 50) are formed. A front surface protective member (20) is disposed on a front surface (10a) of the substrate (10) and a back surface protective member (20) is disposed on a back surface (10b) of the substrate (10), and a laminate (80) is formed. The laminate (80) is integrated by a lower pressure being applied while heating at a lower temperature, compared to the temperature and pressure in the process of forming the interlayer connecting members (40 and 50).

FIG. 4

